

10-25-1999

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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

YING-LANG WANG, CHUN-CHING TSAN,  
JOWEI DUN & HUNG-JU CHIENAdditional name(s) or conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance

☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ other \_\_\_\_\_
Execution Date: 5/10/99

2. Name and address of receiving party(ies):

Name: Taiwan Semiconductor Manufacturing Company

Internal Address:

Street Address:

 121 Park Ave. 3  
 Science-Based Industrial Park  
 City: Hsin-Chu Zip:  
 Country: Taiwan, R.O.C.

 Jc625 U.S. PTO  
 09/418032  
 10/14/99
Additional name(s) & address(es) attached? Yes ☐ No ☒

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: 5/10/99A. Patent Application No(s)B. Patent No(s)

09/418032

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: GEORGE O. SAILE

Internal Address: \_\_\_\_\_

Street Address: 20 MCINTOSH DRIVECity: POUGHKEEPSIE State: NY ZIP: 126036. Total no. of applications and patents involved: 17. Total fee (37 CFR 3.41): \$ 40.00☐ Enclosed☒ Authorized to be charged to deposit acct.8. Deposit account number: 19-0033

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9. Statement and signature.

To the best of my knowledge and belief the foregoing information is true and correct and any attached copy is a true copy of the original document

GEORGE O. SAILE

Name of Person Signing

George O. Saile

Signature

October 12, 1999

Date

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For ☒ U.S. and/or ☒ Foreign Rights

For ☒ Application or ☐ U.S. Patent

By ☒ Inventor(s) or ☐ Present Owner

### ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

#### ASSIGNOR:

YING-LANG WANG

Type or print name of ASSIGNOR

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Address

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Nationality

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Pao-Shan Hsiang, Hsin-Chu

U.S.A.

Nationality

HUNG-JU CHIEN

Type or print name of ASSIGNOR

SF. No. 139, Po-Ting Rd.

Address

Hsin-chu, Taiwan.

Republic of China

Nationality

#### ASSIGNEE:

**Taiwan Semiconductor Manufacturing Co. Ltd.**

**121 Park Ave. 3**

**Science-Based Industrial Park**

**Hsin-Chu, Taiwan, R.O.C.**

**Taiwan, R.O.C.**

Nationality

and the successors, assigns and legal representatives of the ASSIGNEE

(complete one of the following)

☒ the entire right, title and interest

☐ an undivided \_\_\_\_\_ percent (\_\_\_%) interest for the United States and its territorial possessions  
(check the following box/f foreign rights are also to be assigned)

☒ and in all foreign countries

in and to any and all improvements which are disclosed in the invention entitled:

**A Low Temperature Process For Forming Intermetal Gap-Filling Insulating Layers In Silicon Wafer Integrated Circuitry**

and which is found in

- (a) ☒ U.S. patent application executed on even date herewith
- (b) ☐ U.S. patent application executed on \_\_\_\_\_
- (c) ☐ U.S. application serial no. \_\_\_\_\_ filed on \_\_\_\_\_
- (d) ☐ U.S. patent no. \_\_\_\_\_ issued \_\_\_\_\_  
(also check (e) if foreign application(s) is also being assigned)
- (e) ☐ and any legal equivalent thereof in a foreign country, including the right to claim priority

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, or substitute, thereof, and as to letters patent any re-issue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I / We have signed this

May 10, 1989 (Date of signing)

**WARNING** Date of signing must be the same as the date of execution of the application if item (a) was checked above.

Ying - Cang, Wang  
Signature of ASSIGNOR(S)  
Chun - Ching, Tsan  
Joc. D.  
Hung - Ju, Chien

If ASSIGNOR is a legal entity complete the following information

\_\_\_\_\_  
Type or print the name of the above person authorized to sign on  
behalf of ASSIGNOR

\_\_\_\_\_  
Title

Note: No witnessing, notarization or legalization is necessary, if the assignment is notarized or legalized then it will only be prima facie evidence (35 USC 261). Use next page if notarization is desired.

\_\_\_\_ Notarization of Legalization Page Added.